

IN THE CLAIMS:

1. - 8. (Previously Canceled)

9. (Currently amended) A solder configuration, comprising a pad having a surface characterized as non-planar and circuitous and adapted to receive solder, thereby forming a portion of a solder joint, said non-planar and circuitous surface being disposed within an upon which an intermetallic boundary interface is disposed, said intermetallic region encompassing boundary interface defining a separation between said surface of said pad and said solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and circuitous, whereby a crack forming in said solder proximate a boundary with said intermetallic region is influenced to proceed in a direction substantially parallel to said non-planar and circuitous surface along said interface with a non-planar, circuitous path, thereby lengthening its travel, and preventing failure of said solder joint.

10. (Currently amended) A solder configuration, comprising a pad having a surface characterized as a non-planar, serpentine surface adapted to receive solder, thereby forming a portion of a solder joint, said non-planar and serpentine surface being disposed within an upon which an intermetallic boundary interface is disposed, said intermetallic region encompassing boundary interface defining a separation between said surface of said pad and said solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and serpentine, whereby a crack forming in said solder proximate a boundary with said intermetallic region is influenced to proceed in a direction substantially parallel to said non-planar and serpentine surface along said interface with a non-planar, serpentine path, thereby lengthening its travel, and preventing failure of said solder joint.

11. - 14. (Withdrawn)